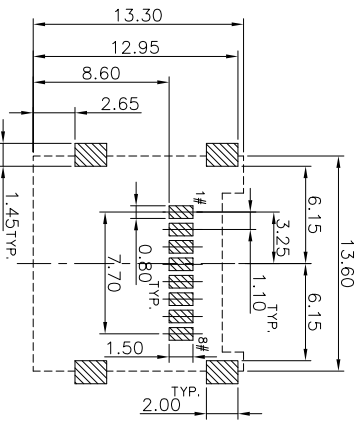
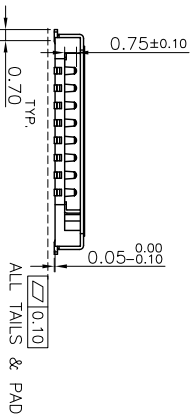
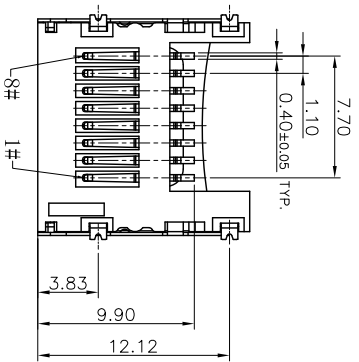


SHELL LOCK



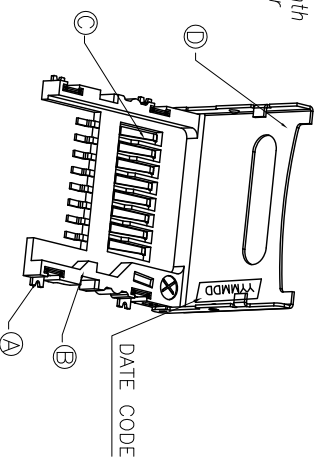
RECOMMENDED PCB PATTERN LAYOUT
TOLERANCE: ±0.05



REV.	ECN NO OR DESCRIPTION	REVISED	DATE
A	PDR NO:1T00201-2A	Tom	2010.05.11
B	ECN NO:S100813	ANDY	2010.10.25

SPECIFICATIONS:

- MATERIAL : HOUSING:HIGH TEMPERATURE THERMOPLASTIC. UL94V-0-BLACK
SHELL:STAINLESS STEEL.
CONTACT:COPPER ALLOY.
SOLDER PAD: COPPER ALLOY.
- PLATING:
CONTACT: GOLD FLASH PLATED OVER,
50u" Min. Ni.
50u" Min. Ni.
SOLDER PAD:100u" Min. Sn PLATING OVER
50u" Min. Ni.
- ELECTRICAL CHARACTERISTIC:
CONNECT RESISTANCE:80 MILLIOHMS/PRE PIN Max.
INSULATION RESISTANCE:1000 MEGAOHMS Min.
VOLTAGE WITHSTAND:500V AC for 1 minute
- TO CONFORM TO SINGATRON HARADOUS SUBSTANCE FREE SPEC.
- HALOGEN FREE PRODUCT IDENTIFICATI MARK ON JACK: ©
- HALOGEN FREE PRODUCT IDENTIFICATION LOGO ON PACKING: Ⓢ
- DATE CODE: YMMD



Pin No	Name	Type	DESCRIPTION
1	DAT2	I/O/PP	Data Line [bit2]
2	CD/DAT3	I/O/PP	Card Detect Data Line [bit3]
3	CMD	PP	Command Response
4	VDD	S	Supply Voltage
5	CLK	I	Clock
6	VSS	S	Supply Voltage Ground
7	DAT0	I/O/PP	Data Line [bit0]
8	DAT1	I/O/PP	Data Line [bit1]

E	MYLAR	1	MYLAR 0.06t	
D	Shell	1	STAINLESS STEEL.	清洗
C	Contact	8	COPPER ALLOY.	Gold Flash
B	Housing	1	HIGH TEMPERATURE THERMOPLASTIC. UL94V-0.	BLACK
A	Solder Pad	4	COPPER ALLOY.	Sn:100u"min Ni:50u"min
NO	DESCRIPTION	QTY	MATERIAL	PLATING & COLOR
UNLESS OTHERWISE SPECIFIED TOLERANCES				
DECIMALS: ANGLES:				
X	:±0.5	X	:±2°	
XX	:±0.3	XX	:±1°	
XXX	:±0.2			
TITLE			T-FLASH CARD CONNECTOR	
DWN	ANDY	PART NO.	2CA2000-002111	
CHKD	LUSSSEN	SCALE	1:1 UNIT: mm	
APVD	TONY	SIZE: A3	SHEET: 10F1 REV: B	
CUSTOMER COPY				

信音企業股份有限公司
Singatron Enterprise Co., Ltd.